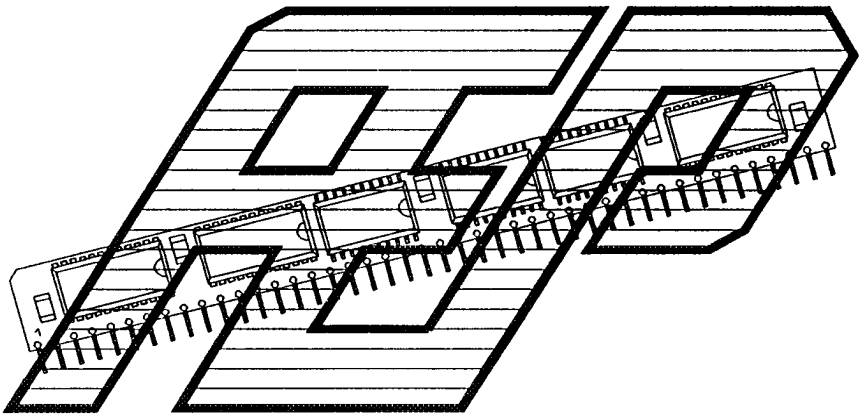
- >> *65,536 x 9 Organization*
- >> *On board BUFFERS for all address and control lines*
- >> *Low profile design, 0.5 inch stand-off height.*
- >> *Double sided to maximize bit density*
- >> *Completely Static operation*
- >> *TTL compatible*
- >> *Uses single +5V power supply*



# 64 KILO-WORD BY 9 BIT HIGH SPEED STATIC RAM MODULE WITH ON-BOARD BUFFERS

DESCRIPTION:

The AEPSS64K9B is a high speed, high density 64 kilo-word by 9 bit static random access memory module with on board buffering of all address and control lines. Physically it consists of an FR4 PC material substrate surface mounted with nine 64K x 1 high speed static RAM ICs, three 244 type buffer ICs, five 0.18 microfarad decoupling capacitors, and 44 press-in I/O pins in a single-inline-package format.

The module can use any of the 64K x 1 SRAMs with SOJ lead packages and standard pin-out made by any of a variety of manufacturers. A wide range of access speeds are available.

Performance specifications and electrical characteristics are determined by the IC devices used. These items can vary according to the type and manufacturer of the components. The necessary information is obtained from the IC vendors' data sheets, like those attached, or from their data books.

Mechanical dimensions are 0.50 in. high by 4.40 in. long by 0.32 in. wide. The I/O pins are on 0.1 inch center spacing.

A 256K x 9 version is also available. Both versions can be made in a by 8 bit organization on request.

**ADVANCED ELECTRONIC PACKAGING**
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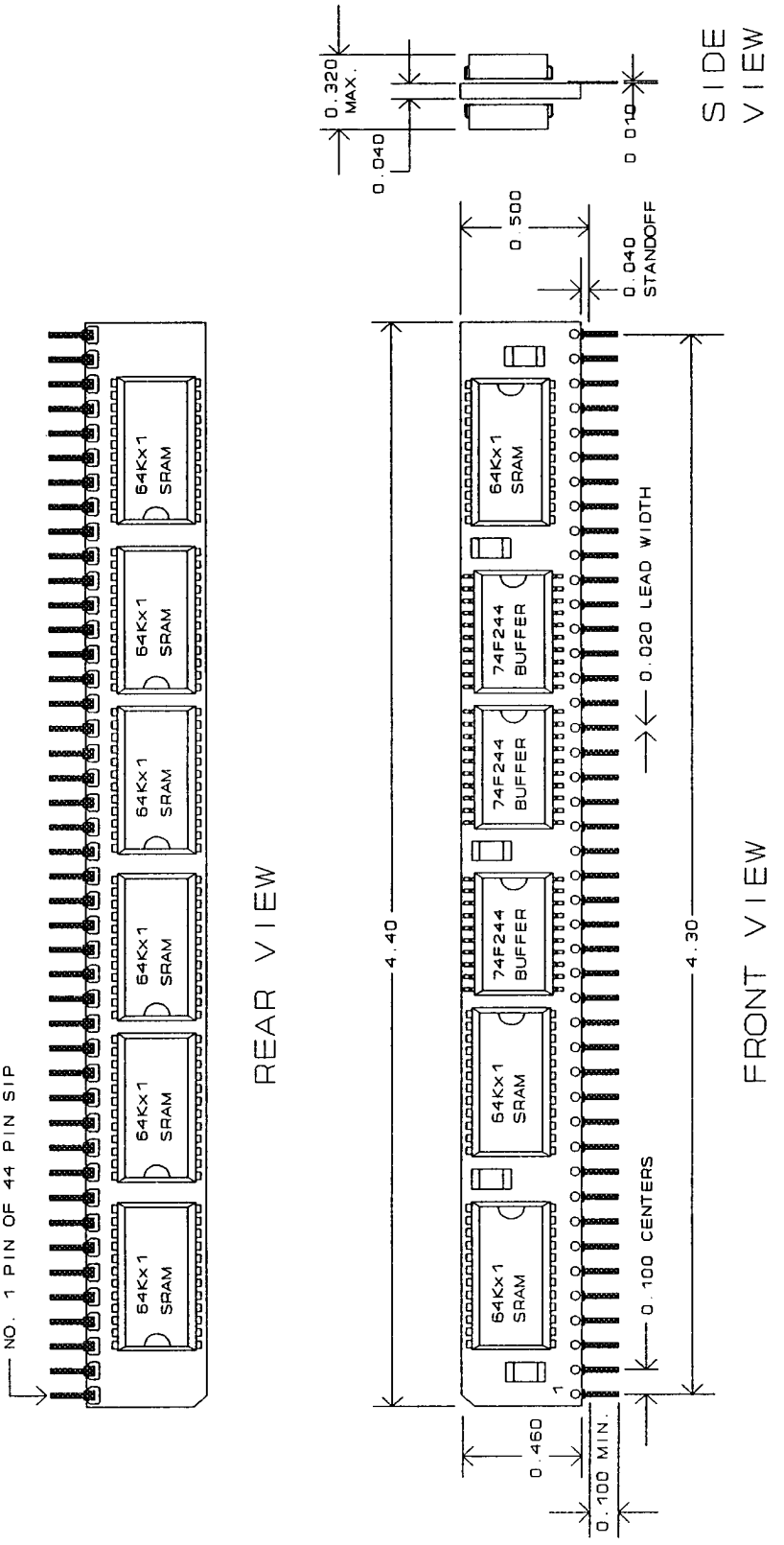
(714) 969-1150 FAX: (714) 536-0936

# ADVANCED ELECTRONIC PACKAGING
# AEPSX64K9B
# HIGH SPEED SRAM MODULE WITH BUFFERS

DIMENSION IN INCHES, TOLERANCE: +/-0.010 UNLESS SPECIFIED.

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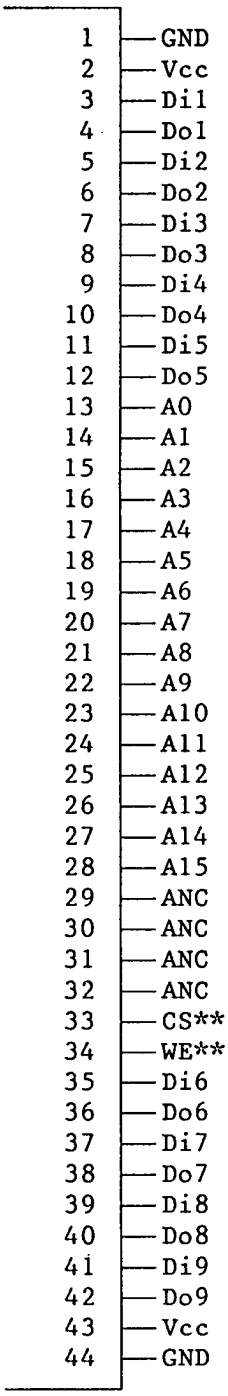
# BUFFERED HIGH SPEED 64K x 9 STATIC RAM
# PIN-OUT CONFIGURATION




| | |
|---|---|
| A1 - A15 | ADDRESS INPUTS |
| Di1 - Di9 | DATA INPUTS |
| Do1 - Do9 | DATA OUTPUTS |
| CS** | CHIP SELECT** |
| WE** | WRITE ENABLE** |
| ANC | NO CONNECT* |
| Vcc | POWER +5V |
| GND | GROUND |

* reserved for next generation address lines

** ACTIVE LOW

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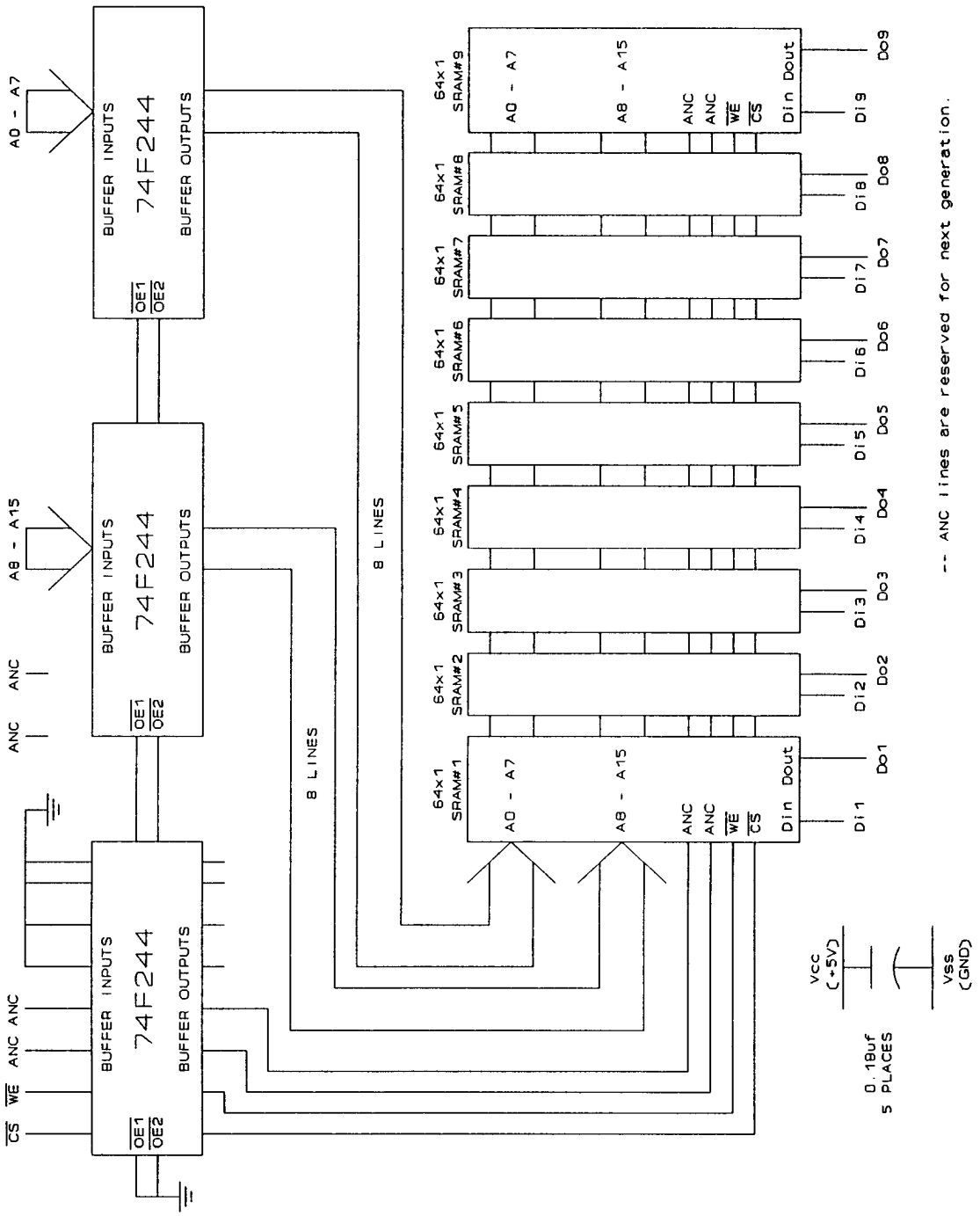
AEP BUFFERED HIGH SPEED 64Kx9 SRAM
FUNCTIONAL DIAGRAM

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## PART NUMBERING CHART

| 64K x 9 SRAM | Vertical lead pins | Horizontal lead pins |
|---|---|---|
| 25ns SRAM ICs | AEPSS64K9B-25 | AEPSH64K9B-25 |
| 35ns SRAM ICs | AEPSS64K9B-35 | AEPSH64K9B-35 |
| 45ns SRAM ICs | AEPSS64K9B-45 | AEPSH64K9B-45 |
| 55ns SRAM ICs | AEPSS64K9B-55 | AEPSH64K9B-55 |

Buffer notes:
The standard buffer used is the 74F244 which can add 6.5ns to the access speed in worst case. AEP may substitute the 74FCT244A or equivalent (4.3ns worst case) if more readily available. To order this faster buffer specifically add -FCT to the end of the above part number.

Memory notes:
Memory access speeds specified in the part numbers are maximums for the SRAM ICs used. AEP reserves the right to use faster rated devices unless requested not to. As an example, 35ns parts may be substituted for 45ns parts depending on stocks on hand.

Due to the rapidly progressing nature of SRAM development, devices with access speeds other than those listed could become available at any time. Check with AEP.

Vendor notes:
The IC device specification information which may be included is typical and does not limit AEP to that vendor. The actual devices used will be equivalent depending on price, availability, and customer requirements. AEP will gladly use or exclude particular manufacturers upon request. However, this might affect module price.

Upgrade notes:
The moudle will be available in a 256K x 9 configuration. See Pin-Out chart for the reserved address lines to be activated, all else will be the same.

Disclaimers:
The information in this document has been carefully checked and is believed to be reliable. However, Advanced Electronic Packaging Inc. assumes no responsibility for inaccuracies. AEP also reserves the right to change products or specifications without notice.